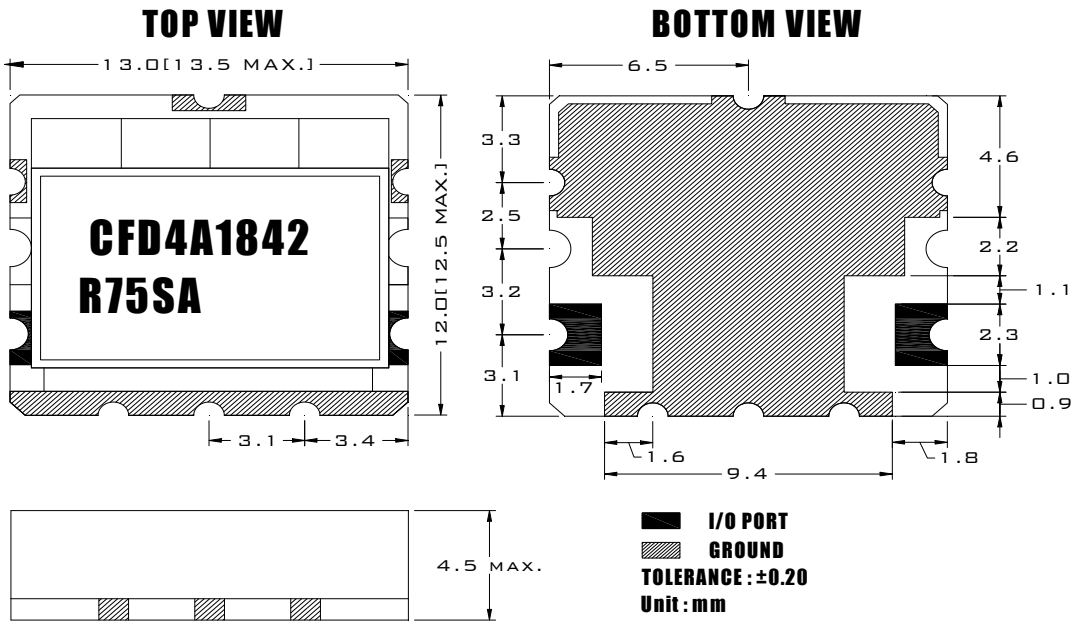
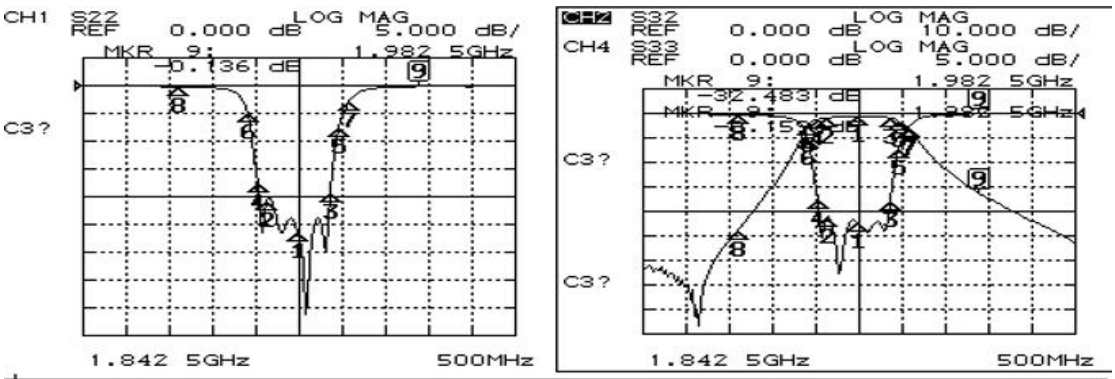
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	1842.5	MHz
Bandwidth [BW]	fo ±37.5 [1805.5 ~ 1880]	MHz
Insertion Loss in BW	2.5	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	2.0dB min @ fo ±47.5 [1795~ 1890]	MHz
	5.0dB min @ fo ±57.5 [1785~ 1900]	MHz
	32dB min @ fo ±140 [1702.5~ 1982.5]	MHz
	dB min @ fo ± [~]	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40℃ to +85℃	

Mechanical Specification



Plot Data

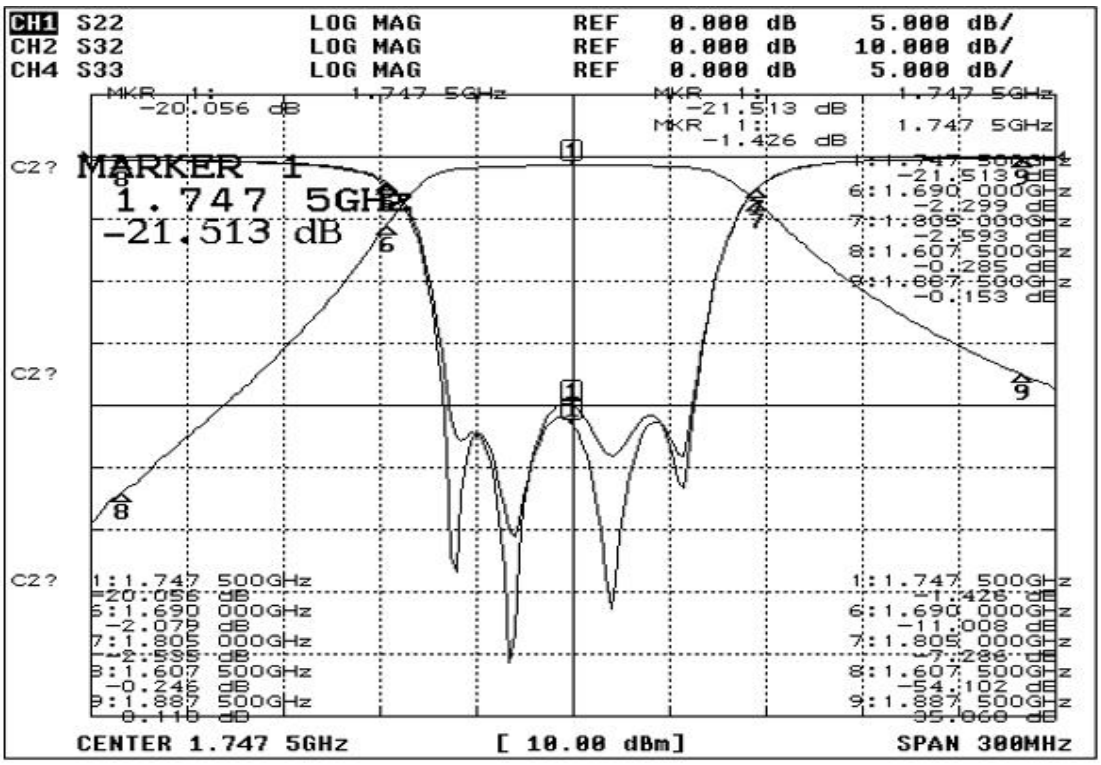


CH2 MARKER LIST

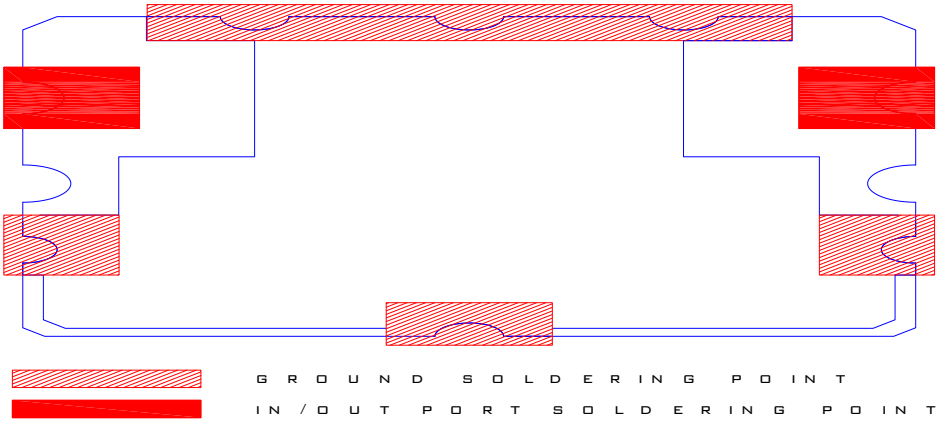
1:	1.842 500GHz	-1.354	dB
2:	1.805 000GHz	-1.800	dB
3:	1.880 000GHz	-1.804	dB
4:	1.795 000GHz	-2.431	dB
5:	1.890 000GHz	-6.173	dB
6:	1.785 000GHz	-5.580	dB
7:	1.900 000GHz	-6.410	dB
8:	1.702 500GHz	-48.008	dB
9:	1.982 500GHz	-32.503	dB
10:			

CH4 MARKER LIST

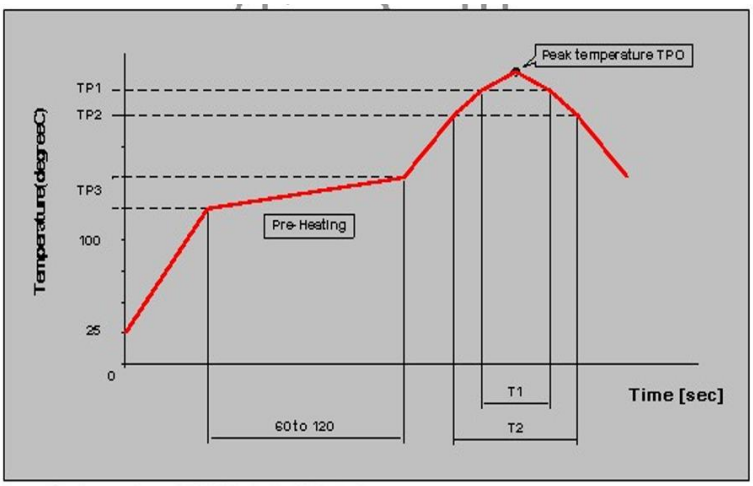
1:	1.842 500GHz	-22.324	dB
2:	1.805 000GHz	-21.409	dB
3:	1.880 000GHz	-17.843	dB
4:	1.795 000GHz	-17.797	dB
5:	1.890 000GHz	-7.454	dB
6:	1.785 000GHz	-5.283	dB
7:	1.900 000GHz	-2.965	dB
8:	1.702 500GHz	-0.232	dB
9:	1.982 500GHz	-0.160	dB
10:			



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180